

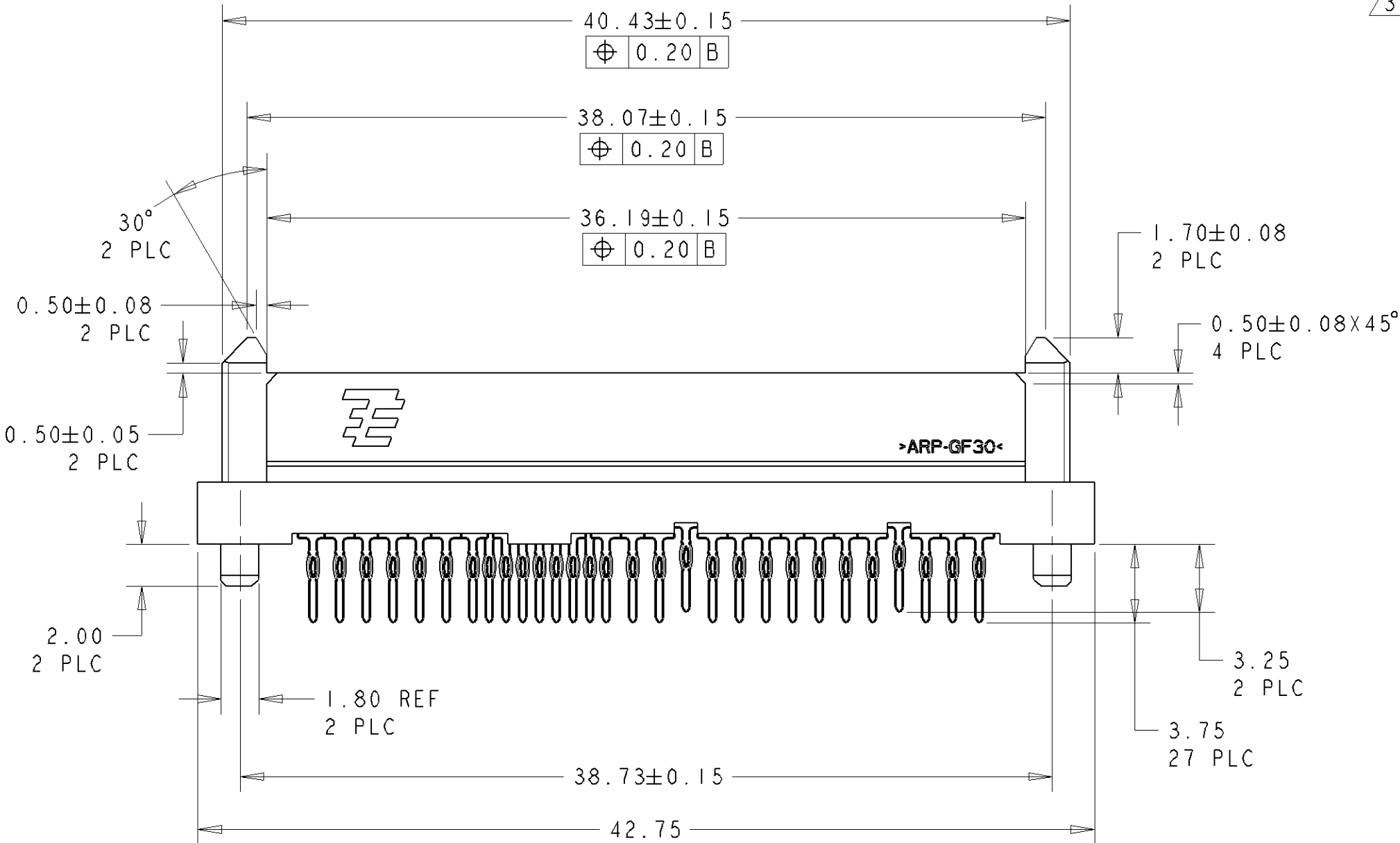
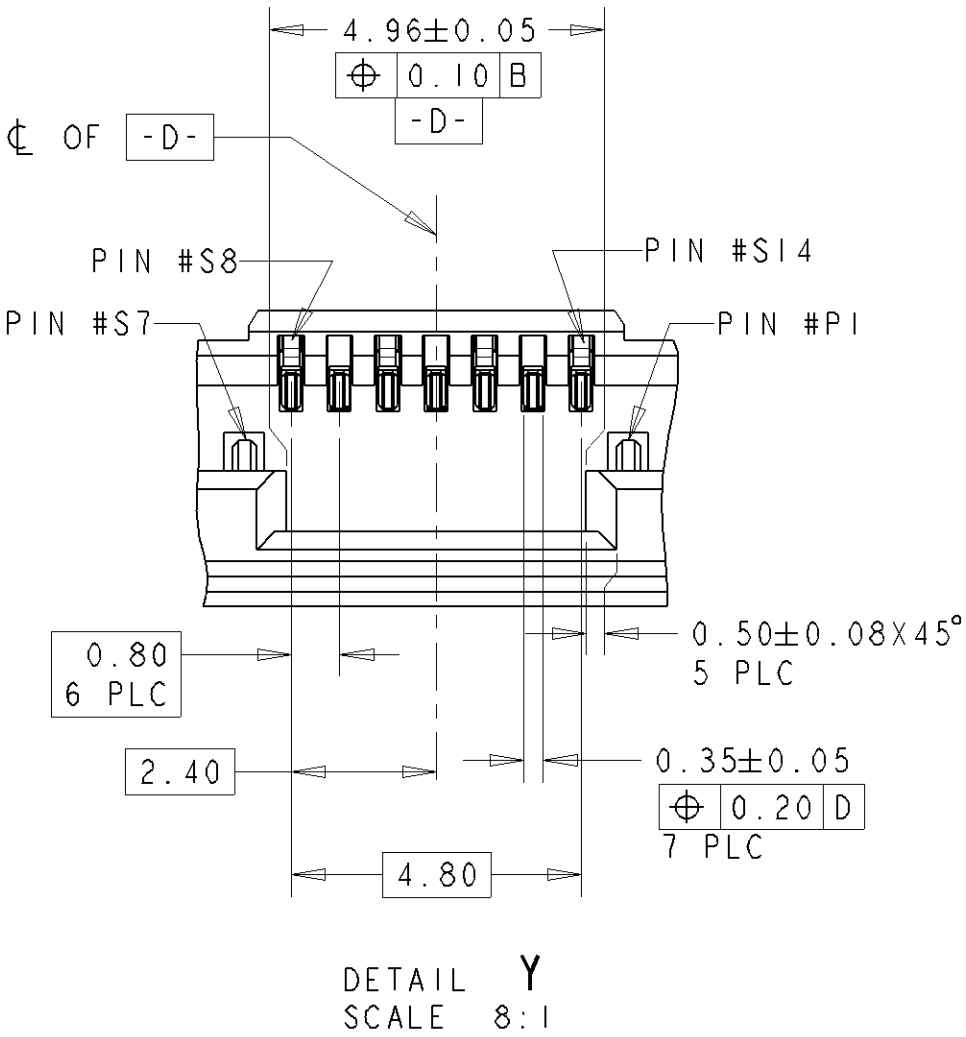
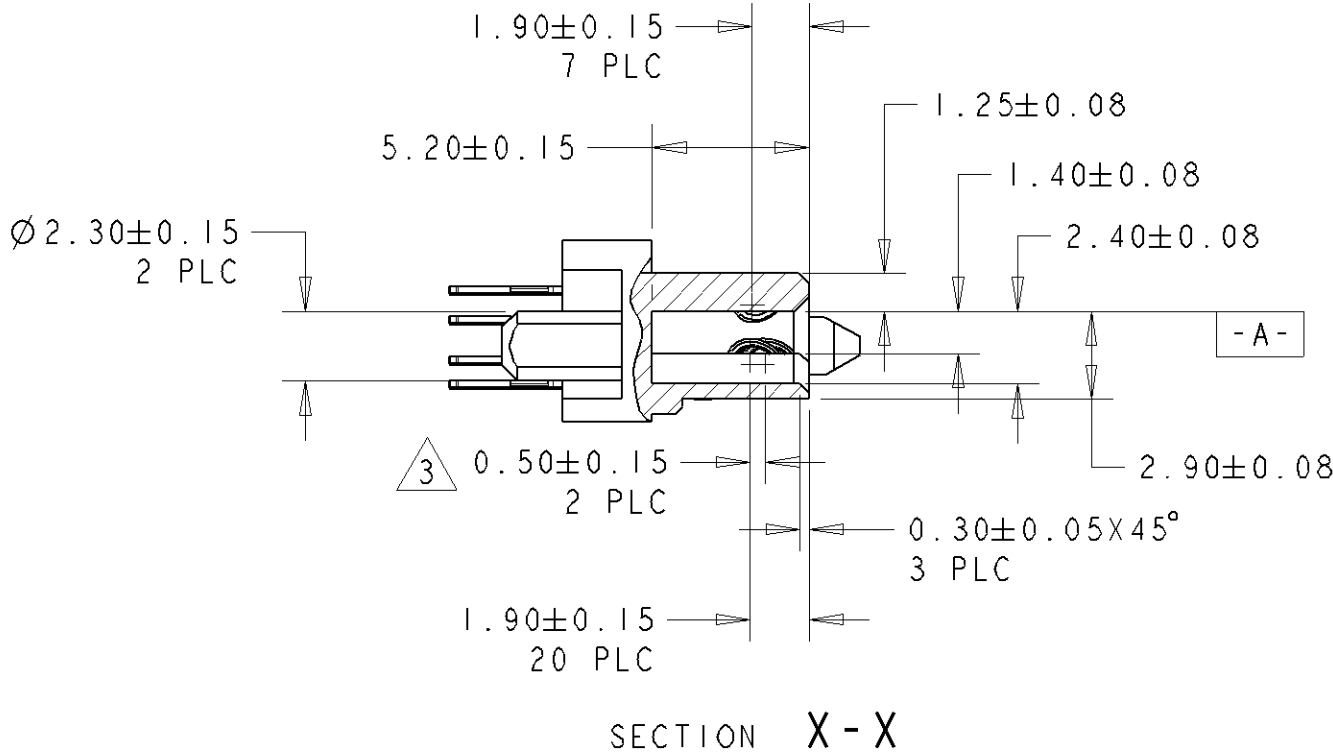
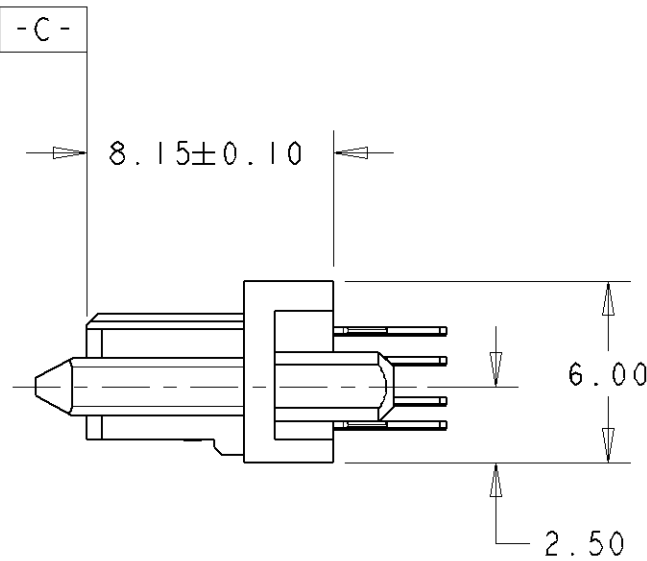
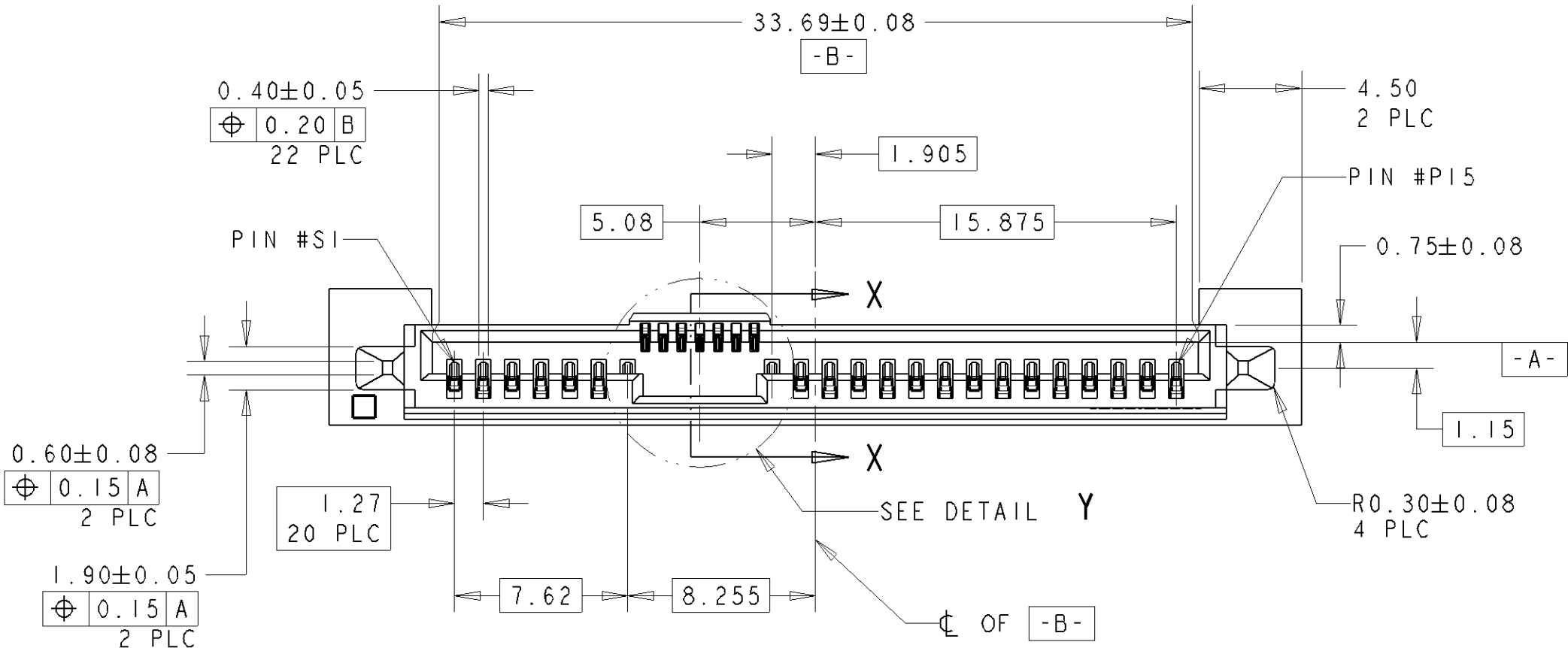
LOC	DIST	REVISIONS				
		P	LTR	DESCRIPTION	DATE	OWN APVD
DY	-	B		REVISED ECR-10-012418	11JUN10	PTY LSF

- NOTES:
- 1

MATERIAL:
HOUSING: HIGH TEMP THERMOPLASTIC, UL94V-0,
COLOR: BLACK
CONTACT: COPPER ALLOY
BOARDLOCK: COPPER ALLOY
- 2

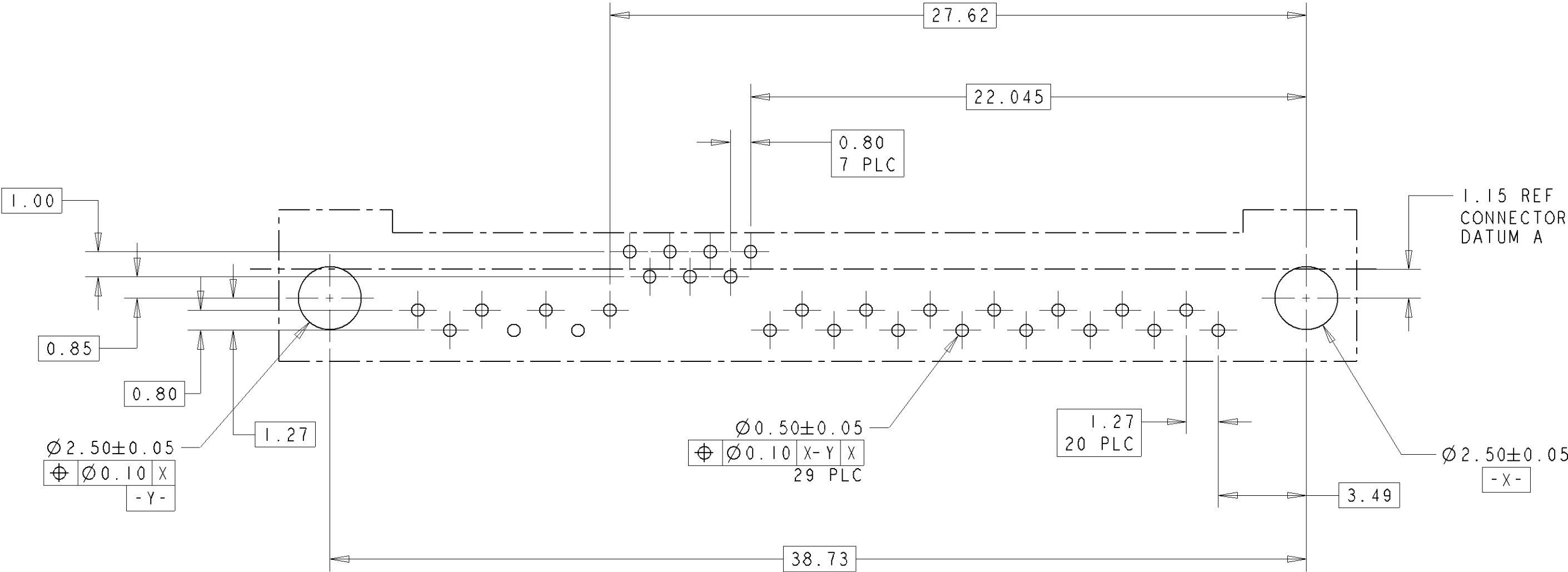
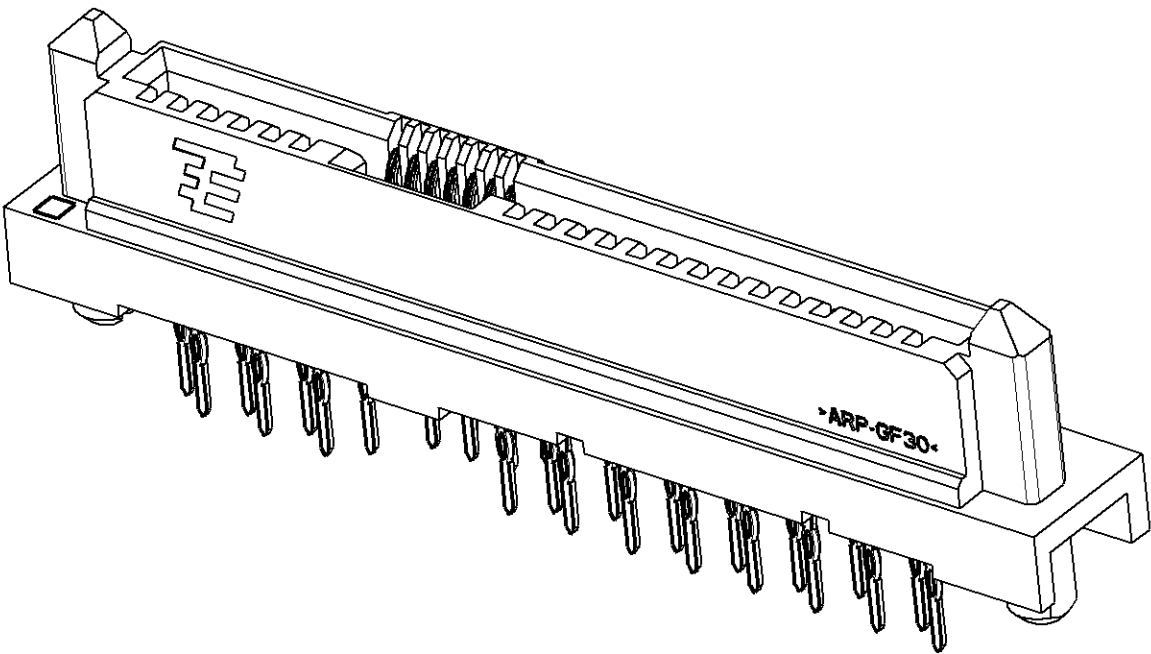
FINISH:
CONTACT AREA: MIN 0.76um GOLD PLATING
SOLDERTAIL: MIN 2.54um MATTE TIN PLATING
UNDERPLATE: MIN 1.27um NICKEL PLATING
- 3

PIN #P4 AND #P12 ONLY



THIS DRAWING IS A CONTROLLED DOCUMENT FOR AMP INCORPORATED. IT IS SUBJECT TO CHANGE AND THE CONTROLLING ENGINEERING ORGANIZATION SHOULD BE CONTACTED FOR THE LATEST REVISION.		OWN SK LEAW 31JUL2006	tyco Tyco Electronics Singapore Pte. Ltd.		
DIMENSIONS: mm		CHK SF LEONG 31JUL2006			
		APVD SF LEONG 31JUL2006	NAME SAS BACKPLANE RECEPTACLE, VERTICAL, PRESS-FIT		
		PRODUCT SPEC 108-51067			
MATERIAL 1		APPLICATION SPEC 114-51013	SIZE A2	CAGE CODE 00779	DRAWING NO C=1735368
		FINISH 2	WEIGHT -	SCALE 4:1	SHEET 1 OF 2 REV B
		CUSTOMER DRAWING	1735368-1 PART NUMBER		

LOC	DIST	REVISIONS				
DY	-	P	LTR	DESCRIPTION	DATE	DWN
						APVD
		-		SEE SHEET 1	-	-



RECOMMENDED PCB LAYOUT
MIN BOARD THICKNESS: 1.44mm
SCALE 6:1

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		CHK	SF LEONG	31 JUL 2006						
DIMENSIONS: mm		APVD	SF LEONG	31 JUL 2006	NAME	SAS BACKPLANE RECEPTACLE, VERTICAL, PRESS-FIT				
		PRODUCT SPEC								
		108-51067								
		APPLICATION SPEC								
MATERIAL -		114-51013			SIZE	CAGE CODE		DRAWING NO		
		WEIGHT -			A2	00779		C=1735368		
TOLERANCES UNLESS OTHERWISE SPECIFIED:		CUSTOMER DRAWING			SCALE		SHEET		REV	
					4:1		2		OF 2	
0 PLC ±-										
1 PLC ±-										
2 PLC ±0.20										
3 PLC ±-										
4 PLC ±-										
ANGLES ±3°										
FINISH -										